

Small Signal Product

Surface Mount Schottky Barrier

FEATURES

- Designed for mounting on small surface
- Extremely thin/leadless package
- Low capacitance
- Low forward voltage drop
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21







0603



- Case: 0603
- Terminal: Gold plated, solderable per
- MIL-STD-750, method 2026
- Polarity: Indicated by cathode band
- Weight: 3 mg (approximately)
- Marking code: BF

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)					
PA	RAMETER	SYMBOL	VALUE	UNIT	
Repetitive Peak Reverse Voltage		V _{RRM}	30	V	
DC Reverse Voltage		V _R	30	V	
RMS Reverse Voltage		V _{R(RMS)}	21	V	
Average Forward Current		Ι _ο	200	mA	
Repetitive Peak Forward Current		I _{FRM}	300	mA	
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rate Load		I _{FSM}	600	mA	
Power Dissipation		Pd	150	mW	
Forward Voltage	I _F = 0.1 mA		0.24		
	I _F =1 mA		0.32		
	I _F = 10 mA	V _F	0.40	V	
	I _F = 30 mA		0.50		
	I _F = 100 mA		1.00		
Reverse Leakage Current	V _R = 25 V	I _R	2	μA	
Typical Capacitance Between Terminals $V_R = 1 \text{ V}$, f = 1.0 MHz Reverse Voltage		CJ	10	pF	
Reverse Recovery Time			F		
$(I_F = I_R = 10 \text{mA}, I_{RR} = 0.1 \times I_R, I_R)$	R _L =100Ω)	t _{rr}	5	ns	
Junction Temperature		TJ	-65 to +125	°C	
Storage Temperature		T _{STG}	-65 to +125	°C	

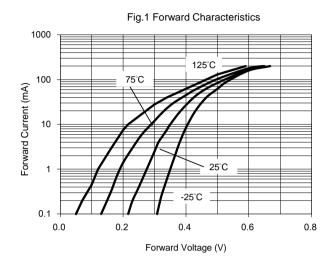


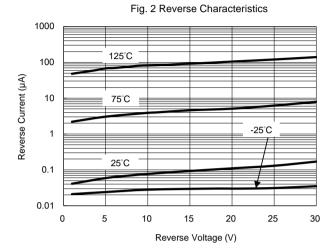
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RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)





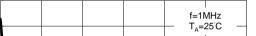


Fig. 3 Capacitance Between Terminals Characteristics

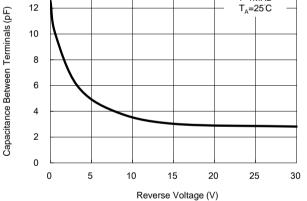
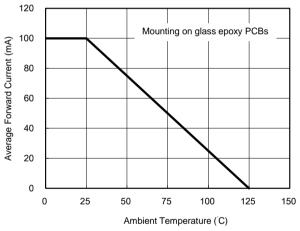


Fig. 4 Current Derating Curve





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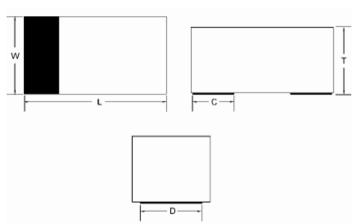
ORDERING INFORMATION					
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
TSS54U	RG	G	0603	4K / 7" Reel	

Note: Whole series with green compound

EXAMPLE						
EXAMPLE		PACKING CODE	PACKING CODE	DESCRIPTION		
PART NO.	PART NO.	PACKING CODE	SUFFIX			
TSS54U RGG	TSS54U	RG	G	Green compound		

PACKAGE OUTLINE DIMENSION

0603



DIM.	ι	Jnit (mm)		Unit (inch)	
	Min	Тур.	Max	Min	Тур.	Max
L	1.60	-	1.80	0.063	-	0.071
W	0.80	-	1.00	0.031	-	0.039
Т	0.70	-	0.85	0.028	-	0.033
С	-	0.45	-	-	0.018	-
D	-	0.70	-	-	0.028	-



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